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FOR IMMEDIATE RELEASE

Press Release

YINCAE Launches Snap Cure, Highly filled ,100% No-Clean Flux Residue Compatible Underfill: UF 120HA

(Albany, NY) 10/08/2025 — YINCAE, a leading manufacturer of electronic materials, has announced the launch of its new product, UF 120HA. The innovative underfill material is specifically designed to provide a fast flow, lower-temperature cure for high-throughput applications and is 100% compatible with all no-clean flux residue. Additionally, it is reworkable, making it an ideal solution for manufacturers looking to reduce costs and improve production efficiency.

Key Benefits:

- ❖ Fully compatible with all no-clean solder paste flux residue
- ❖ Eliminating the cleaning process and its pollution
- ❖ Lower temperature snap cure (<120 °C)
- ❖ Passes 5×260 °C reflow without any deformation of the solder joint
- ❖ Better than all competitors' underfill with a cleaning process
- ❖ Lower CTE and able to flow into small gaps
- ❖ Reworkable
- ❖ Large cost savings

"Our team is excited to introduce UF 120HA to the market," said YINCAE's Chief Technology Officer. "We understand the challenges facing manufacturers today, and we have designed this product to address those challenges head-on. UF 120HA offers fast flow, low-temperature cure, compatibility with all no-clean flux residue, and reworkability, making it an ideal solution for a wide range of high-throughput manufacturing applications."

For more information on YINCAE's UF 120HA, or to learn more about what YINCAE offers, please email us at: info@yincae.com. You can also find more information by visiting our website at: www.yincae.com

Founded in 2005 & headquartered in Albany, New York, YINCAE Advanced Materials is a leading manufacturer and supplier of thermal interface materials, underfill solutions, die attach adhesives, electronic materials, & high-performance coatings used in microchip & optoelectronic devices. YINCAE products provide new technologies to support manufacturing processes from wafer level, to package level, to board level and final devices while facilitating smarter and faster production and supporting green initiatives.

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